

## **ABSTRACT**

An optical semiconductor component has multiple conducting wire holders, multiple chip carriers secured, multiple semiconductor chips, a first curved surface made of the conducting wire holders, the semiconductor chips being placed at its focus, multiple connecting components made of the conducting wire holders, and a second curved surface surrounded by a package body, the semiconductor chips being placed at its focus. The chip carriers are independent components and have a multi-layer structure. The middle layer is an insulator used to separate the chip from the conducting wire holder electrically or thermally. Hence, when connected with a metal radiator, the chip carrier does not cause electric leakage. Further, the connecting components of the present invention are mutually independent, which can provide multiple photodiodes with different driving voltages to connect with each other in series or parallel.

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